



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: NAKAMURA, et al.
Serial No.: 10/500,119
Filed: June 17, 2005
For: CONNECTION BOARD, AND MULTI-LAYER WIRING BOARD,
SUBSTRATE FOR SEMICONDUCTOR PACKAGE AND
SEMICONDUCTOR PACKAGE USING CONNECTION
BOARD, AND MANUFACTURING METHOD THEREOF
Group AU: 2841
Examiner: I. Patel
Confirm. No: 7910

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

January 17, 2007

Sir:

In response to the Office Action mailed November 20, 2006, please amend
the above-identified application as listed in the following, and as set forth on the
following pages:

Amendments to the Claims; and

Remarks are included following the amendments.